

HY9045 Addition electronic potting compound

Usage:

Insulation, waterproof and bonding of general electronic components.

Characteristics:

Addition electronic potting compound is a kind of two components (1:1 mixing ratio) addition cure silicone with the Characteristics of heat-conducting, low viscosity, Inherent flame resistance, waterproofing, etc. It can cure both at room temperature and heated temperature and the curing time can be accelerated by higher temperature.

Application:

- Applying for the surface of PC (Poly-carbonate), PP, ABS, PVC, Metal, etc.
- High powered electronic encapsulation and DC/DC module and circuit board which requires heat dissipation and high temperature resistance.
- Insulation, waterproof and bonding of general electronic components.
- Filling for LED, LCD electronic display, circuit board, PCB substrate, etc.
- Outdoor protection for LED screen.

Standard Datasheet:

Product Model		HY-9045
Properties index		Part A Part B
Appearance		Gray fluid White fluid
Before curing	Mixed Viscosity (mPa.s)	2500~3500
Features operation	Mix Ratio (A:B)	1:1
	Operating Time (25°C /mins)	60~120
	Curing time (hrs, 25°C)	8
	Curing time (hrs, 80°C)	20
	Hardness (shore A)	45±5
After Curing	Linear expansibility[m/ (m·K)]	≤2.2×10 ⁻⁴
	Thermal Conductivity[W (m·K)]	≥0.8
	Dielectric Strength (kV/mm)	≥25
	Dielectric permittivity (1.2MHz)	3.0~3.3
	Volume resistivity (Ω·cm)	≥1.0×10 ¹⁶
	Fire Resistance	UL94-V1

Notes and operation instructions:

1) The following material may hinder the curing of electronic potting compound silicone, so please use after the test. When necessary, please clean the application areas.

- Organotin compound or Condensation silicone with organotin
- Sulphur, sulfide and sulfur rubber materials.
- Amine compounds as well as contains the amine materials.
- Pewters solder flux

2) Deaeration the mixture in vacuum pump under 0.08 MPa for 3-5 minutes. Then the mixture could be used for pouring.

3) Please note that the thickness of the silicone affects the curing time. If the silicone used is a little thick, then the curing time will be a little longer. The temperature also affects the curing time. When in lower temperature, we suggest customers appropriately heat the mixture to accelerate vulcanization.

4) Above electronic potting compound silicone should be sealed storage. The mixture should be used up to avoid causing waste.

5) Above silicone belongs to non-dangerous goods, but keep away from mouth and eyes.

6) When it gets stratified after a period of storage, please mix it evenly before using, this does not affect the performance.

Packaging:

40Kgs/pail as a set (Part A 20Kg + Part B 20Kg)

SHELF LIFE AND TRANSPORTATION

1. Twelve(12) months when stored at 25C in tightly closed original packages.
2. This kind of product is non-dangerous product, which could be transported as general chemicals.
3. Storage beyond the expired date does not necessarily mean that the product is no longer usable. In this case however, the properties required for the intended use must be checked for quality assurance reasons.